



i n v e n t

Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model
[List multiple models if applicable.]

Compaq Presario CQ4000 PC Series

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	3
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	The QTY may vary from different PSU Models	8
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)	system fan, cooler, PSU fan	3
Components and parts containing toner and ink,	Include the cartridges, print heads, tubes, vent	0

including liquids, semi-liquids (gel/paste) and toner	chambers, and service stations.	
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

1.3 Markings for plastic parts greater than 25 grams

Plastic Part Name	Plastic Part Description	Weight (grams)	ISO 11469:2000 Plastic Part Mark	Optional: Photo
P_MAIN_BEZEL_EARTH	main bezel	121.0	>ABS<	
Fan Frame	CPU fan frame	35.6g	>PBT-GF30-FR(17)<	

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #1 Trox screw driver	T10
Description #2 Soldering Iron	
Description #3	
Description #4	
Description #5	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

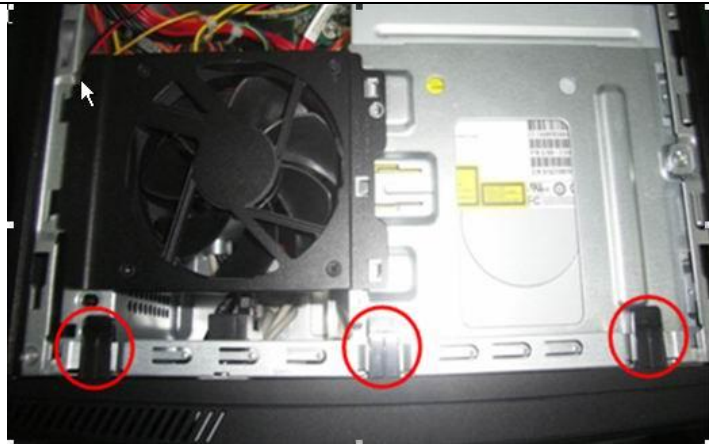
1. Remove cover from the unit
2. Remove front bezel
3. Remove HDD&ODD cage
4. Remove PSU and PCI & PCI-E cards
5. Remove all cable from PCA
6. Take off Cooler
7. Take off CMOS battery
8. Cut off wire tie
9. Electrolytic Capacitors location
10. Heat the solder of Electrolytic Capacitors Heat the solder of Electrolytic Capacitors

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).



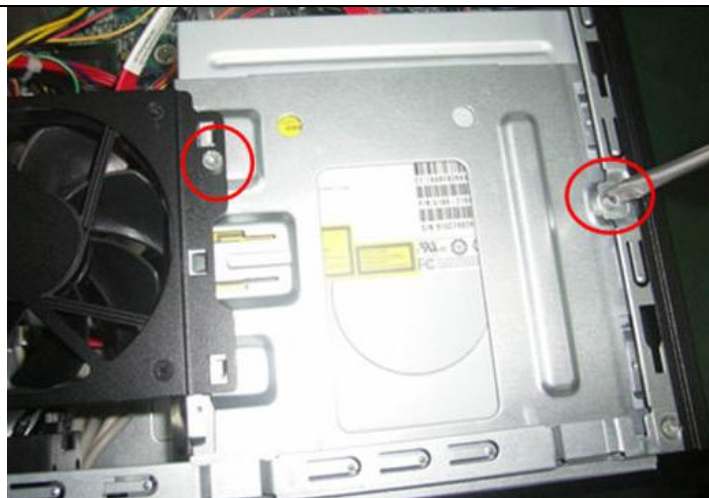
1 Remove cover from the unit

Rotate screw to open the cover



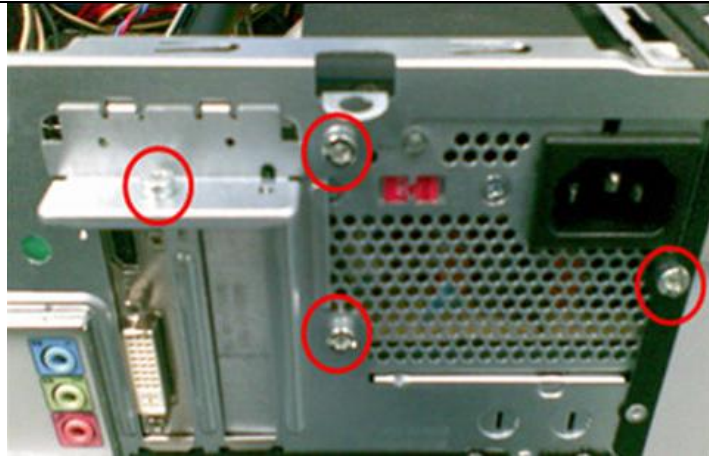
2 Remove front bezel

Pull the three latch of front bezel to remove it from chassis



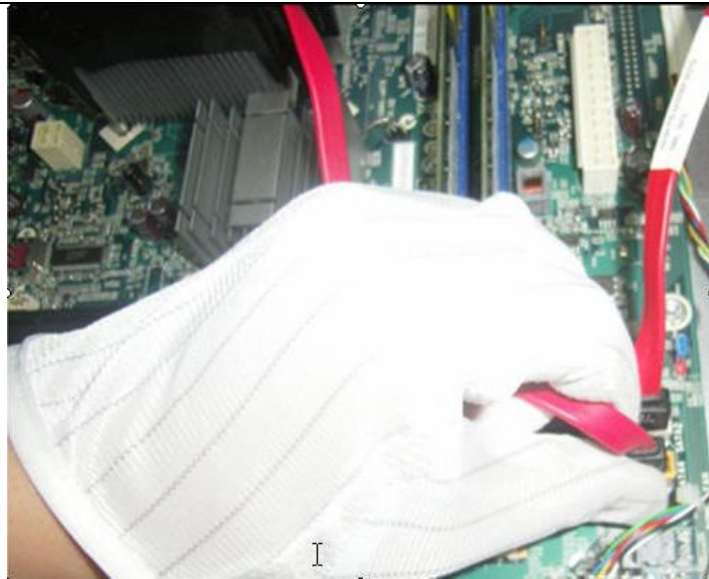
3 Remove HDD&ODD cage

Use screw driver to take off the screw (5pcs) as shown in the photo



4 Remove PSU and PCI & PCI-E cards

Use screw driver to take off the screw (3pcs for PSU and 1pc for PCI&PCI-E cards) as shown in the photo



5 、 Remove all cable from PCA

Press the button to pull power cords off

Pull the other cords off PCA



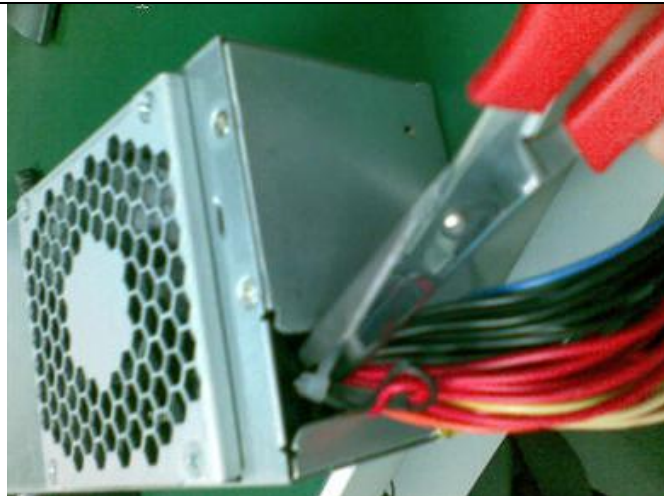
6 Take off Cooler

Rotate screw driver to loose screw and then take the cooler off PCA



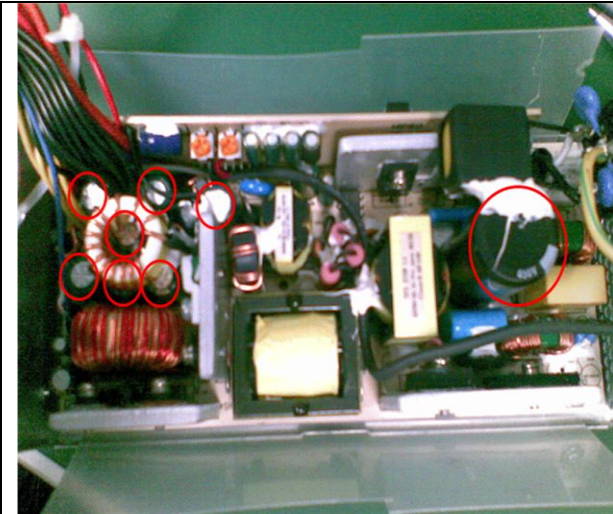
7 Take off CMOS battery

Pull the battery holder as shown in the photo, and then the battery will off the PCA



8 Cut off wire tie

9 Electrolytic Capacitors location



**10 Heat the solder of Electrolytic Capacitors
Heat the solder of Electrolytic Capacitors**